

Dual N-Channel Enhancement Mode MOSFET

1. Product Information

1.1 Features

- ☑ Surface-mounted package
- ☑ Low Thermal Resistance

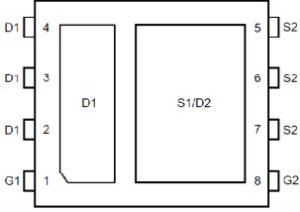
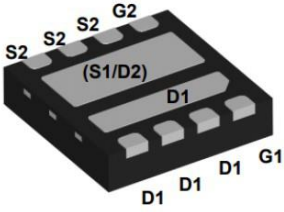
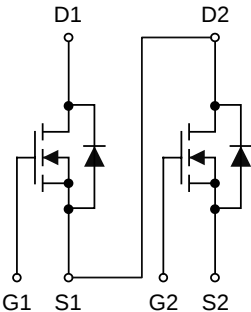
1.2 Applications

- ☑ Motor drivers
- ☑ High power inverter system

1.3 Quick reference

- ☑ $BV \geq 30\text{ V}$
- ☑ $R_{DS(ON)} \leq 6.3\text{ m}\Omega @ V_{GS} = 10\text{ V}$
- ☑ $P_{tot} \leq 35\text{ W}$
- ☑ $R_{DS(ON)} \leq 8.2\text{ m}\Omega @ V_{GS} = 4.5\text{ V}$
- ☑ $I_D \leq 50\text{ A}$

2. Pin Description

Pin Description	Simplified Outline	Symbol
	 DFN3x3	

3. Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	Drain-Source Voltage	$T_A=25^{\circ}\text{C}$	30	-	V
V_{GS}	Gate-Source Voltage	$T_A=25^{\circ}\text{C}$	-	± 20	V
I_D^*	Drain Current	$T_A=25^{\circ}\text{C}, V_{GS}=10\text{ V}$	-	50	A
		$T_A=100^{\circ}\text{C}, V_{GS}=10\text{ V}$	-	30	A
$I_{DM}^{*,**}$	Pulsed Drain Current	$T_A=25^{\circ}\text{C}, V_{GS}=10\text{ V}$	-	160	A
P_{tot}^*	Total Power Dissipation	$T_A=25^{\circ}\text{C}$	-	35	W
T_J, T_{stg}	Operating Junction and Storage Temperature		-55	150	$^{\circ}\text{C}$
I_S	Diode Forward Current	$T_A=25^{\circ}\text{C}$	-	50	A
$R_{\theta JA}^*$	Thermal Resistance-Junction to Ambient		-	62.5	$^{\circ}\text{C/W}$

Notes:

- * Surface Mounted on 1 in² pad area, $t \leq 10\text{ sec}$
- ** Pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 1\%$

4. Marking Information

Product Name	Marking
KJ0603CQ	0603C YWWXXX
	3060 YWWXXX

5. Ordering Code

Product Name	Package	Reel Size	Tape width	Quantity	Note
KJ0603CQ	DFN3x3			5000	

Note: KUIJIEXIN defines "Green" as lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900 ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500 ppm by weight; Follow IEC 61249-2-21 and IPC/JEDEC J-STD-020C)

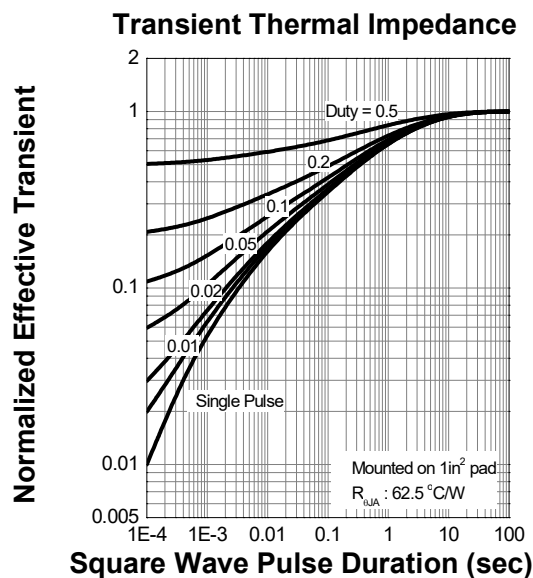
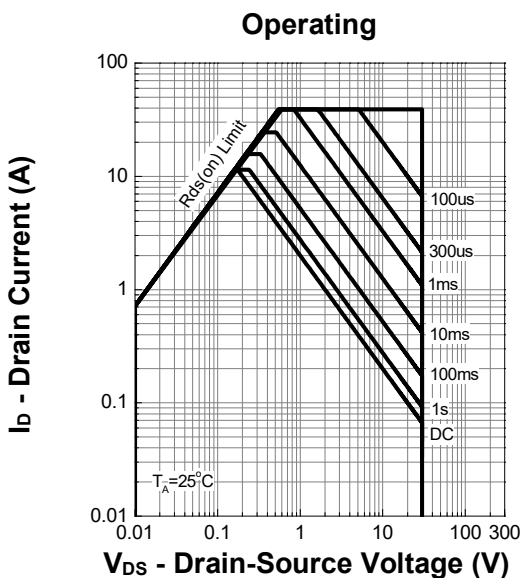
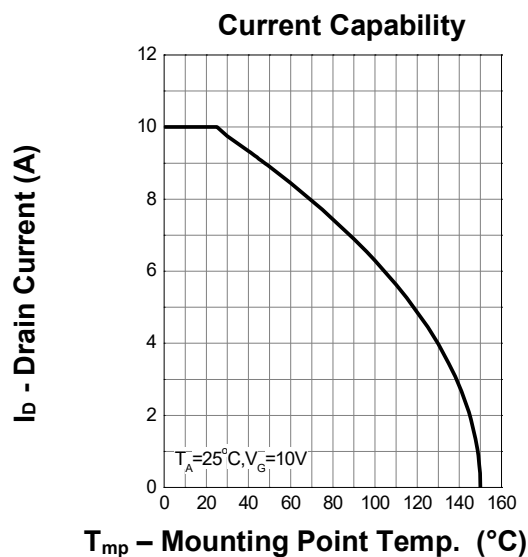
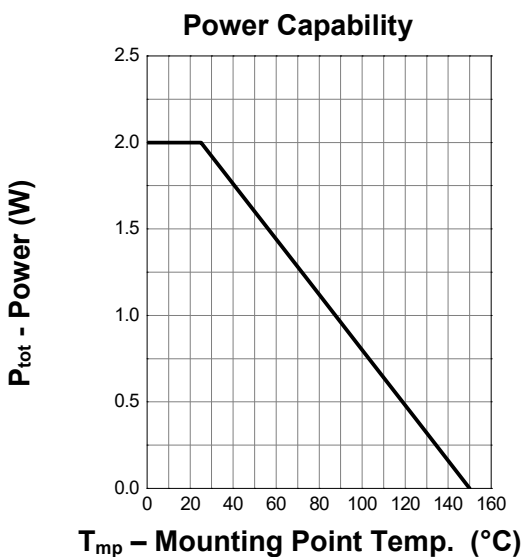
6. Electrical Characteristics (T_A=25°C Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0 V, I _D =250 μA	30	-	-	V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250 μA	1.0	-	2.0	V
I _{DSS}	Drain Leakage Current	V _{DS} =24V, V _{GS} =0 V	-	-	1	μA
		T _J =85°C	-	-	30	μA
I _{GSS}	Gate Leakage Current	V _{GS} =±20 V, V _{DS} =0 V	-	-	±100	nA
R _{DS(ON)} ^a	On-State Resistance	V _{GS} =10 V, I _D =10 A	-	5.7	6.3	mΩ
		V _{GS} =4.5 V, I _D =5 A	-	7.5	8.2	
Diode Characteristics						
V _{SD} ^a	Diode Forward Voltage	I _{SD} =10 A, V _{GS} =0 V	-	-	1.3	V
t _{rr}	Reverse Recovery Time	I _{SD} =10 A, dI _{SD} /dt=100 A/μs	-	34	-	ns
Q _{rr}	Reverse Recovery Charge		-	7.1	-	nC
Dynamic Characteristics ^b						
C _{iss}	Input Capacitance	V _{GS} =0 V, V _{DS} =15 V, Frequency=1 MHz	-	1145	-	pF
C _{oss}	Output Capacitance		-	106	-	
C _{rss}	Reverse Transfer Capacitance		-	87	-	
t _{d(on)}	Turn-on Delay Time	V _{DS} =15 V, V _{GEN} =10 V, R _G =4.5 Ω, R _L =1.5 Ω, I _D =10 A	-	7	-	ns
t _r	Turn-on Rise Time		-	30	-	
t _{d(off)}	Turn-off Delay Time		-	19	-	
t _f	Turn-off Fall Time		-	18	-	
Gate Charge Characteristics ^b						
Q _g	Total Gate Charge	V _{GS} =10 V, V _{DS} =15 V, I _{DS} =10 A	-	22	-	nC
Q _{gs}	Gate-Source Charge		-	5	-	
Q _{gd}	Gate-Drain Charge		-	3.3	-	

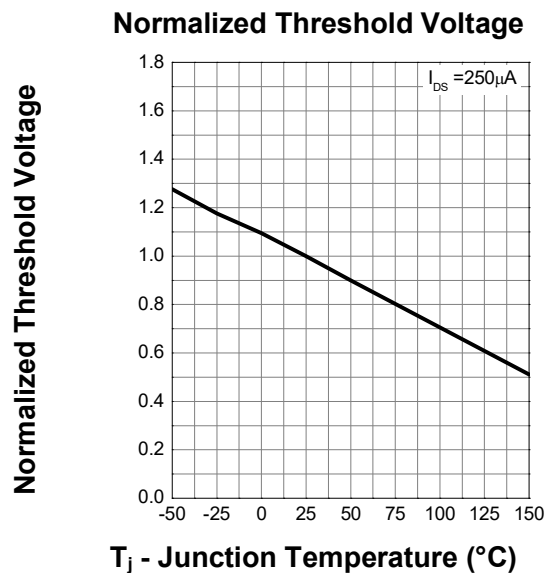
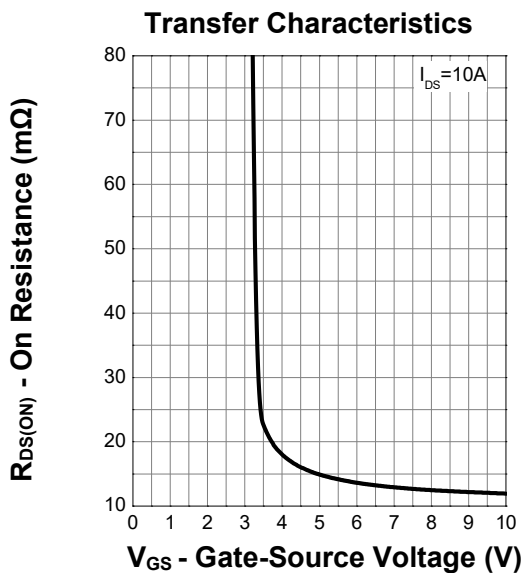
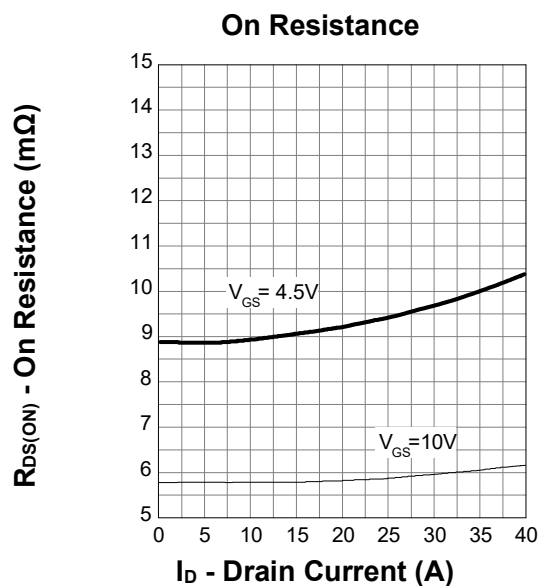
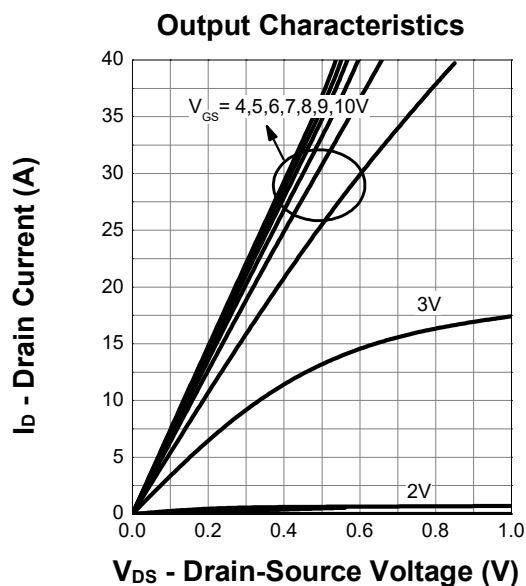
Notes:

- Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%
- Guaranteed by design, not subject to production testing

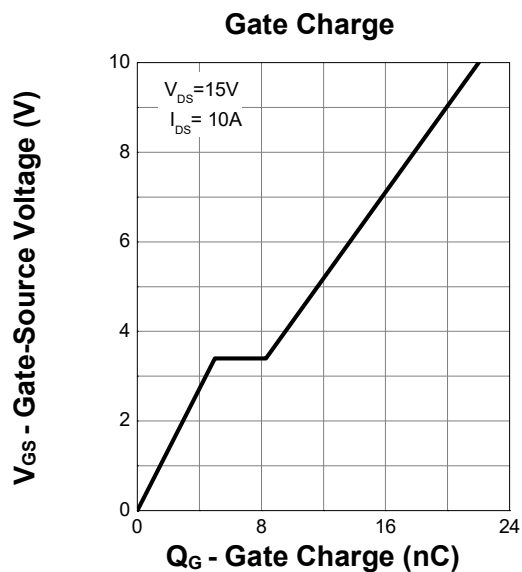
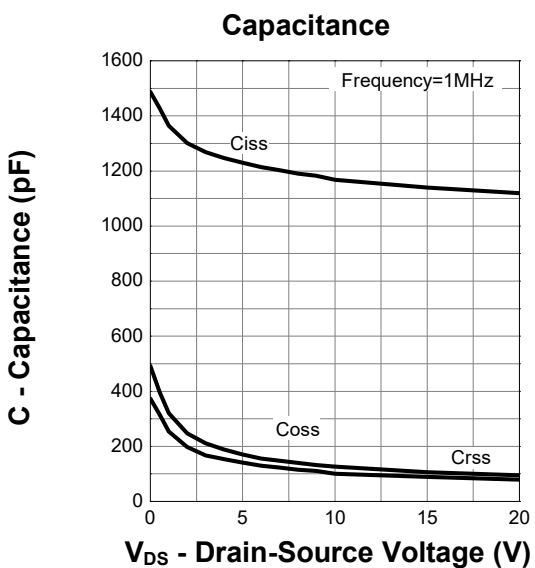
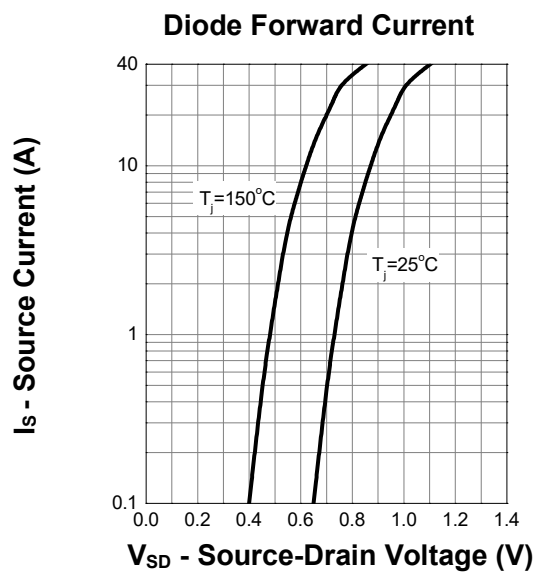
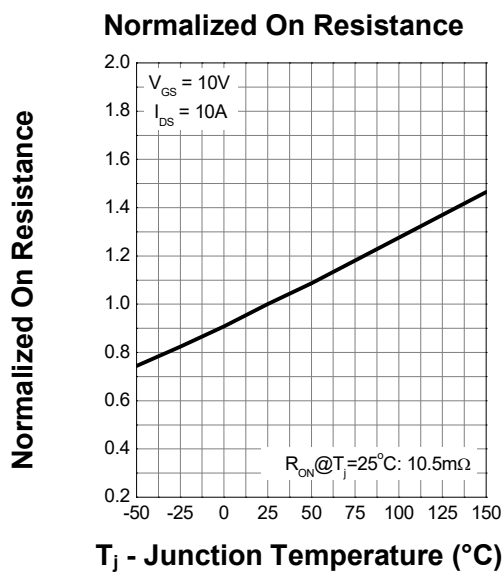
7. Typical Characteristics



7. Typical Characteristics (Cont.)

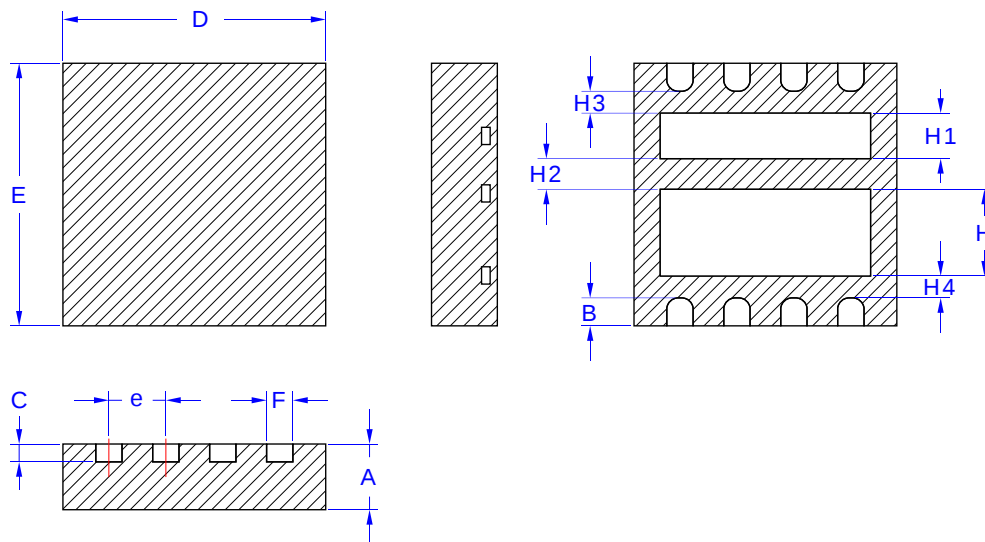


7. Typical Characteristics (Cont.)



8. Package Dimensions

DFN3x3 Package



Symbol	Dimensions in Millimeters		
	MIN	TYP	MAX
A	0.7	0.75	0.80
B	0.27	0.32	0.37
C	0.153	0.203	0.253
D	2.90	3.00	3.10
E	2.90	3.00	3.10
e	0.60	0.65	0.70
F	0.25	0.30	0.35
H	0.89	0.99	1.09
H1	0.42	0.52	0.62
H2	0.25	0.35	0.45
H3	0.15	0.25	0.35
H4	0.15	0.25	0.35
L	2.30	2.40	2.50